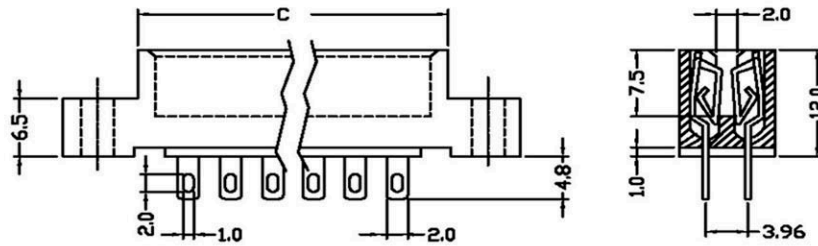
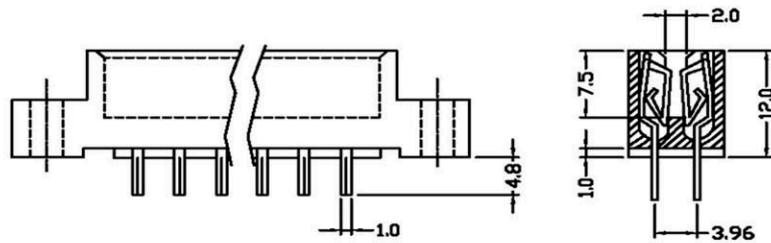


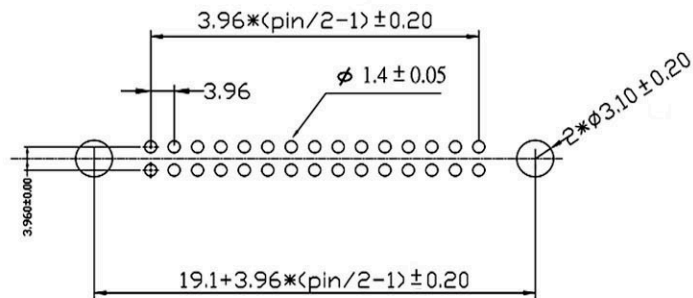
UNLESS OTHERWISE SPECIFIED	
0-10 ±0.2	10-30 ±0.3
30-100 ±0.4	100-300 ±0.5
OVER 300 ±0.6	ANGULAR ±0.5°



SOLDER TYPE → P/NO:C3230-XX"A"PGL00R



DIP TYPE → P/NO:C3230-XX"B"PGL00R



- MATERIAL
INSULATOR: PBT +30% GLASS FIBER (UL94V-0).
CONTACT: PHOSPHOR BRONZE OR BRASS.
PLATING: GOLD OVER NICKEL.

- SPECIFICATION
CURRENT RATING: 3 AMP.
INSULATION RESISTANCE: 5000 MEGOHMS MIN AT 500 VDC.
CONTACT RESISTANCE: 20 MILLIOHMS MAX.
VOLTAGE : 500V FOR ONE MINUTE.

- ENVIRONMENTAL
TEMPERATURE RANGE: -40°C TO +105°C.

Circuit	Dimension					Circuit	Dimension				
	A	B	C	D	E		A	B	C	D	E
10	15.84	24.06	27.40	34.94	41.24	64	122.76	130.98	134.32	141.86	148.16
12	19.80	28.02	31.36	38.90	45.20	70	134.64	142.86	146.20	153.74	160.04
16	27.72	35.94	39.28	46.82	53.12	72	138.60	146.82	150.16	157.70	164.00
20	35.64	43.86	47.20	54.74	61.04	86	166.32	174.54	177.88	185.49	191.48
22	39.60	47.82	51.16	58.70	65.00						
24	43.56	51.78	55.12	62.66	68.96						
28	51.48	59.70	63.04	70.58	76.88						
30	55.44	63.66	67.00	74.54	80.84						
32	59.40	67.62	70.96	78.50	84.80						
36	67.32	75.54	78.88	86.42	92.72						
40	75.24	83.46	86.80	94.34	100.64						
44	83.16	91.38	94.72	102.26	108.56						
48	91.08	99.30	102.64	110.18	116.48						
50	95.04	103.26	106.60	114.14	120.44						
56	106.92	115.14	118.48	126.02	132.32						
60	114.84	123.06	126.40	133.94	140.24						
62	118.80	127.02	130.36	137.90	144.20						

RoHS
Compliant

HSM 玄茂科技股份有限公司
HSUAN MAO TECHNOLOGY CO., LTD.

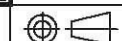
APPD.
核准

DWG.
製圖

DATE

Helen

2018/12/24



SCALE
比例

UNIT
單位

PAGE
張數

TOLERANCE
容許公差

SIZE
紙張尺寸

REV.
版本

1 OF 1

PART NAME 品名

3.96mm CARD EDGE SLOT DUAL ROW XXP
(SOLDER or DIP TYPE) PBT MATERIAL
GOLD FLASH PLATING BLUE INSULATOR ROHS

PART NO.

料號 C3230-XXXPGL00R